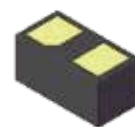


FEATURES

- | 100W Peak Pulse Power per Line (tp=8/20μs)
- | Protects one Bidirectional I/O lines
- | Working voltages : 10 V
- | Low Leakage current
- | Low clamping voltage

APPLICATIONS

- | Cellular Phone Handsets and Accessories
- | Microprocessor based equipment
- | Personal Digital Assistants (PDA' s)
- | Notebooks,Desktops,and Servers
- | Portable Inserumentation
- | Peripherals
- | Pagers



DFN0603



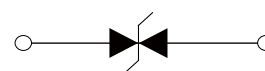
Marking

IEC COMPATIBILITY

- | IEC61000-4-2 (ESD) ±15kV (air), ±10kV (contact)
- | IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

- | | |
|-------------|------------------------------------|
| RoHS | Compliance with 2011/65/EU |
| HF | Compliance with IEC61249-2-21:2003 |



Schematic Symbol

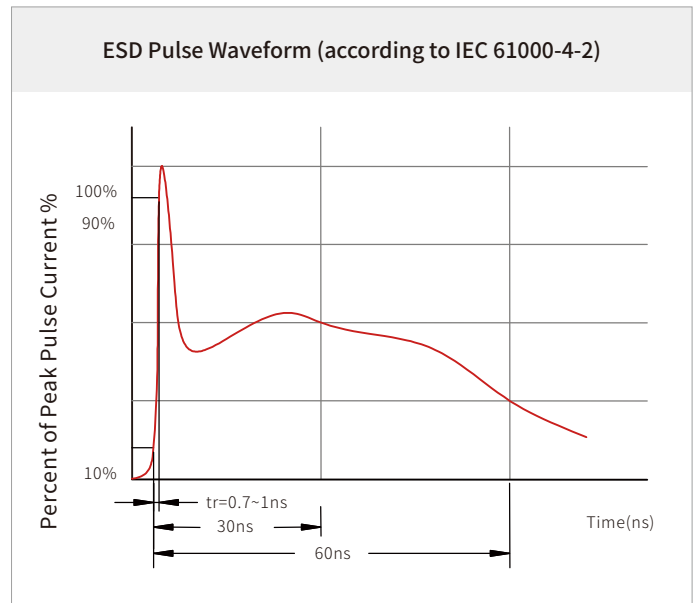
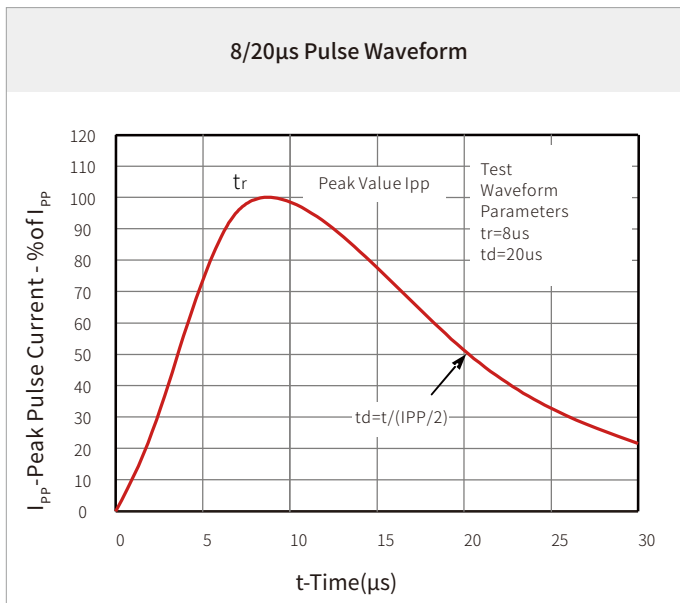
THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
P_{PP}	Peak Pulse Power (tp=8/20μs waveform)	100	Watts
T_J	Operating Temperature Range	-55 to +125	°C
T_{STG}	Storage Temperature Range	-55 to +150	°C

ELECTRICAL CHARACTERISTICS

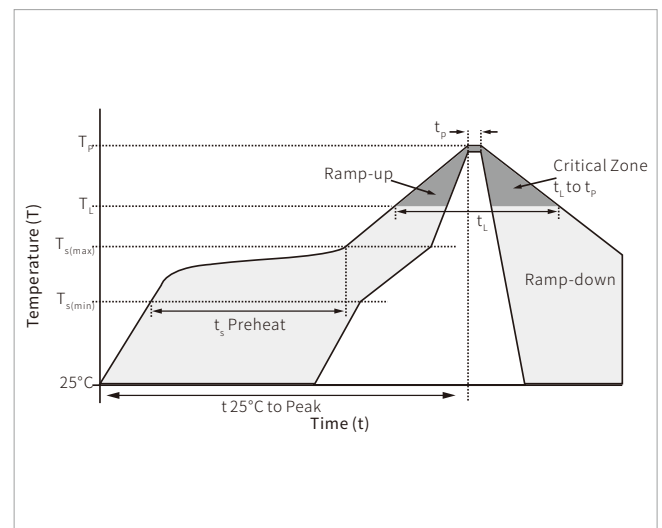
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{RWM}	Reverse Stand-off Voltage				10	V
V_{BR}	Reverse Breakdown Voltage	$I_T=1mA$	12			V
I_R	Reverse Leakage Current	$V_{RWM}=10V$			1	μA
V_C	Clamping Voltage	$I_{PP}=1.65A, tp=8/20μs$			24.5	V
I_{PP}	Peak Pulse Current	tp=8/20μs			1.65	A
C_J	Off State Junction Capacitance	$V_R=0V, f=1MHz$			1.8	pF

CHARACTERISTIC CURVES

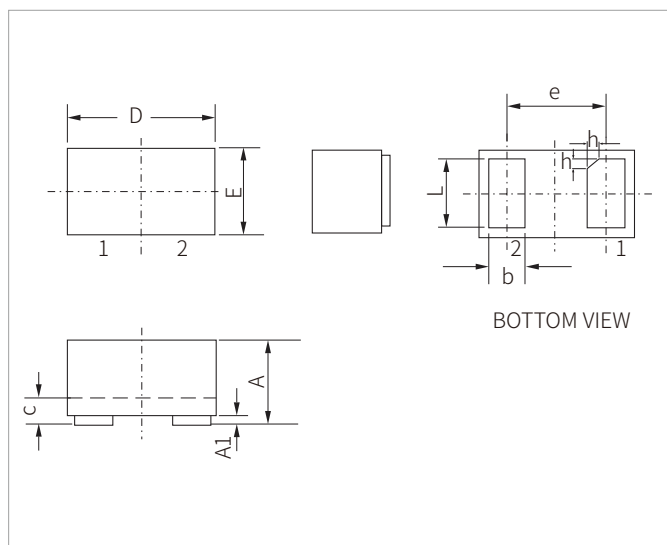


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
Reflow	$T_{s(max)}$ to T_L - Ramp-up Rate	3°C/second max
	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

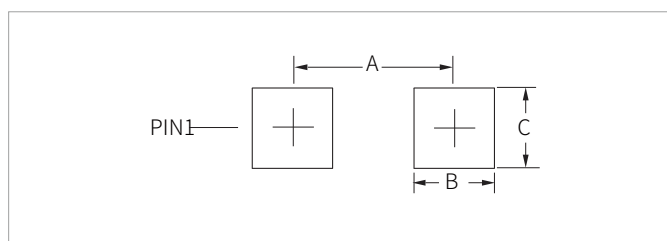


DFN0603 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.28	0.36	0.011	0.014
A1	0	0.05	0	0.002
b	0.13	0.24	0.005	0.009
c	0.05	0.15	0.002	0.006
D	0.55	0.70	0.022	0.028
e	0.35BSC		0.014BSC	
E	0.25	0.35	0.010	0.014
L	0.20	0.30	0.008	0.012
h	0	0.10	0	0.004

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
A	0.38	0.015
B	0.23	0.009
C	0.30	0.012

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE06F10B10LA	DFN0603	15000PCS	7"

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